



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

| Device | V _{(BR)DSS} | R _{DS(ON)} max | I _D max T _A = +25°C |
|---------|----------------------|-------------------------------|--|
| 04 201/ | | $27m\Omega$ @ $V_{GS} = 10V$ | 7.2A |
| Q1 | 30V | $35m\Omega$ @ $V_{GS} = 4.5V$ | 6.0A |
| 00 | -30V | $25m\Omega$ @ $V_{GS} = -10V$ | -7.6A |
| Q2 | | Q2 -30V | $41m\Omega$ @ $V_{GS} = -4.5V$ |

Features and Benefits

- Low Input Capacitance
- Low On-Resistance
- · Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

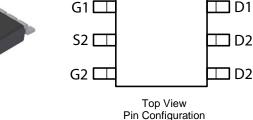
Applications

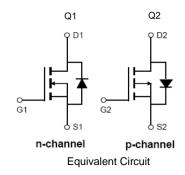
- DC-DC Converters
- Power Management Functions
- Backlighting

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Tin Finish annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (approximate)







Ordering Information (Note 4)

Top View

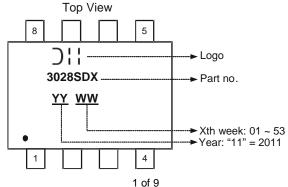
| Part Number | Case | Packaging | | |
|----------------|------|-------------------|--|--|
| DMC3028LSDX-13 | SO-8 | 2,500/Tape & Reel | | |

 \square D1

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



June 2013 © Diodes Incorporated



Maximum Ratings - Q1 and Q2 (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Q1 | Q2 | Units | | |
|--|-----------------|--|----------------|------------|--------------|---|
| Drain-Source Voltage | V_{DSS} | 30 | -30 | V | | |
| Gate-Source Voltage | V_{GSS} | ±20 | ±20 | V | | |
| Continuous Prais Current (Note 5) // 40// | Steady State | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | 5.5 4.1 | -5.8 -4.3 | А |
| Continuous Drain Current (Note 5) V _{GS} =10V | t<10s | $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | I _D | 7.2 5.7 | -7.6 -6.1 | А |
| Maximum Body Diode Forward Current (Note 5) | Is | 2.2 | -2.2 | Α | | |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%) | I _{DM} | 40 | -30 | Α | | |

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | |
|---|------------------------|------------------|-------------|------|
| Total Dower Dissination (Note 5) | T _A = +25°C | Б | 1.2 | W |
| Total Power Dissipation (Note 5) | T _A = +70°C | P_{D} | 0.75 | |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady state | D | 108 | °C/W |
| Internal Resistance, Junction to Ambient (Note 5) | t<10s | R• JA | 65 | |
| Total Power Dissipation (Note 6) | $T_A = +25^{\circ}C$ | PD | 1.5 | W |
| Total Fower Dissipation (Note o) | T _A = +70°C | FD | 0.95 | |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady state | Davi | 85 | °C/W |
| Internal Resistance, Junction to Ambient (Note 6) | t<10s | R _{0JA} | 50 | |
| Thermal Resistance, Junction to Case (Note 6) | Rejc | 14.5 | | |
| Operating and Storage Temperature Range | | T_J, T_STG | -55 to +150 | °C |

Electrical Characteristics – Q1 (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|----------------------|-----|------|------|------------|---|--|
| OFF CHARACTERISTICS (Note 8) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 30 | _ | _ | V | $V_{GS} = 0V, I_D = 250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | 1 | μΑ | $V_{DS} = 24V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 8) | | | | | | • | |
| Gate Threshold Voltage | V _{GS(th)} | 1 | _ | 3 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| Static Drain-Source On-Resistance | В | _ | 19 | 27 | ~ 0 | $V_{GS} = 10V, I_{D} = 6A$ | |
| Static Diain-Source On-Resistance | R _{DS (ON)} | _ | 22 | 35 | mΩ | $V_{GS} = 4.5V, I_D = 5A$ | |
| Diode Forward Voltage | V _{SD} | _ | 0.7 | 1.2 | V | V _{GS} = 0V, I _S = 1.3A | |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | • | |
| Input Capacitance | C _{iss} | _ | 641 | _ | | V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz | |
| Output Capacitance | C _{oss} | _ | 66 | _ | pF | | |
| Reverse Transfer Capacitance | C _{rss} | _ | 51 | _ | | | |
| Gate Resistance | R_G | _ | 2.2 | _ | Ω | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$ | |
| Total Gate Charge (V _{GS} = 4.5V) | Qg | _ | 6 | _ | | V _{DS} = 15V, I _D = 10A | |
| Total Gate Charge (V _{GS} = 10V) | Qg | _ | 13.2 | _ | nC | | |
| Gate-Source Charge | Q _{gs} | _ | 1.7 | _ | IIC | | |
| Gate-Drain Charge | Q _{gd} | _ | 2.2 | _ | | | |
| Turn-On Delay Time | t _{D(on)} | _ | 3.3 | _ | | | |
| Turn-On Rise Time | t _r | _ | 4.4 | _ | | $V_{GS} = 10V, V_{DD} = 15V, R_{G} = 6\Omega,$ | |
| Turn-Off Delay Time | t _{D(off)} | _ | 22.3 | _ | nS | I _D = 1A | |
| Turn-Off Fall Time | t _f | | 5.3 | _ | 1 | | |

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 5. Device mounted on FR-4 substrate PC board, 202 copper, with minimum recommended pate.
 6. Device mounted on FR-4 substrate PC board, 202 copper, with 1inch square copper plate.
 7. I_{AR} and E_{AR} rating are based on low frequency and duty cycles to keep T_J = +25°C
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.



Electrical Characteristics — Q2 (@T_A = +25°C, unless otherwise specified.)

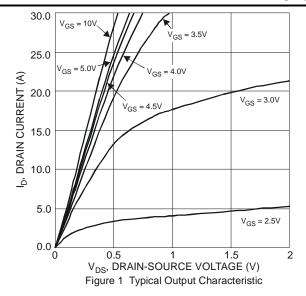
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|---|----------------------|-----|------|------|-------|--|--|
| OFF CHARACTERISTICS (Note 8) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -30 | | _ | V | $V_{GS} = 0V, I_D = -250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | -1 | μA | $V_{DS} = -24V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 8) | | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | -1 | _ | -3 | V | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | |
| Static Drain Source On Besistance | 7 | _ | 21 | 25 | mΩ | $V_{GS} = -10V, I_D = -6A$ | |
| Static Drain-Source On-Resistance | R _{DS (ON)} | _ | 29 | 41 | | $V_{GS} = -4.5V, I_D = -5A$ | |
| Diode Forward Voltage | V _{SD} | _ | -0.7 | -1.2 | V | $V = V_{GS} = 0V, I_S = -1.3A$ | |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | | |
| Input Capacitance | C _{iss} | _ | 1241 | _ | | $V_{DS} = -15V, V_{GS} = 0V$ f = 1.0MHz | |
| Output Capacitance | Coss | _ | 146 | _ | pF | | |
| Reverse Transfer Capacitance | C _{rss} | _ | 110 | _ | | | |
| Gate Resistance | R _G | _ | 14.8 | _ | Ω | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$ | |
| Total Gate Charge (V _{GS} = -4.5V) | Qg | _ | 10.9 | _ | | V _{DS} = -15V, I _D = -7A | |
| Total Gate Charge (V _{GS} = -10V) | Qg | _ | 22 | _ | nC | | |
| Gate-Source Charge | Q _{gs} | _ | 3.5 | _ | nc nc | | |
| Gate-Drain Charge | Q _{gd} | _ | 4.7 | _ | | | |
| Turn-On Delay Time | t _{D(on)} | _ | 9.7 | _ | | V _{GS} = -10V, V _{DD} = -15V, R _{GEN} = 6Ω, | |
| Turn-On Rise Time | t _r | _ | 17.1 | _ | nS | | |
| Turn-Off Delay Time | t _{D(off)} | _ | 60.5 | _ | 115 | $I_D = -7A$ | |
| Turn-Off Fall Time | t _f | _ | 40.4 | _ | | | |

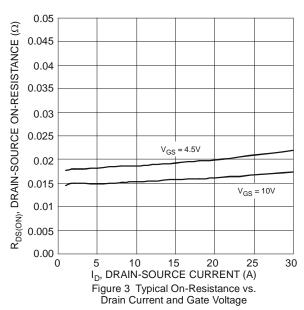
Notes:

^{8.} Short duration pulse test used to minimize self-heating effect. 9. Guaranteed by design. Not subject to product testing.



N-Channel - Q1





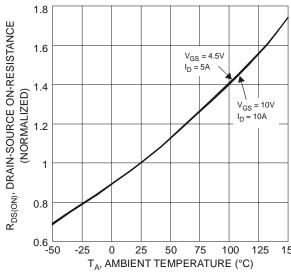
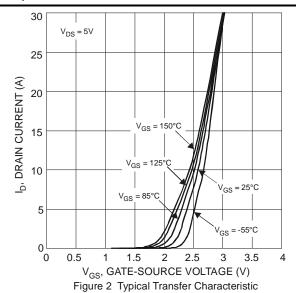


Figure 5 On-Resistance Variation with Temperature



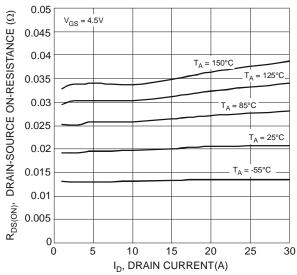


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

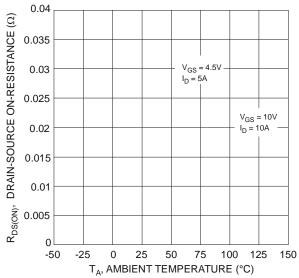


Figure 6 On-Resistance Variation with Temperature



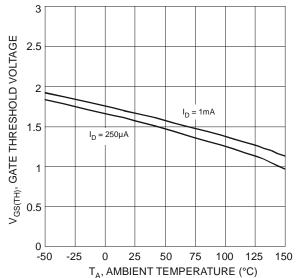


Figure 7 Gate Threshold Variation vs. Ambient Temperature

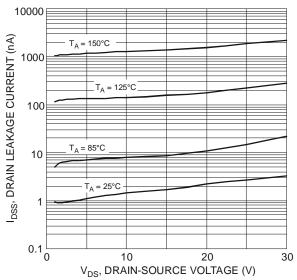


Figure 9 Typical Drain-Source Leakage Current vs. Voltage

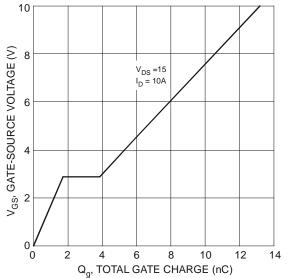
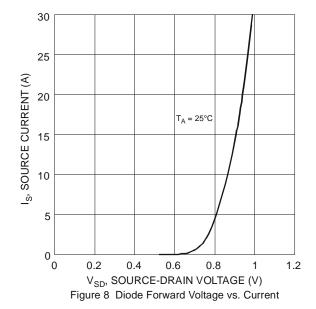
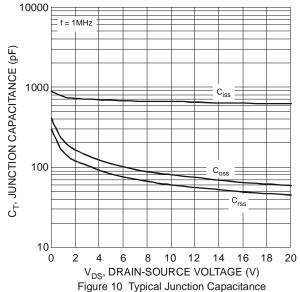


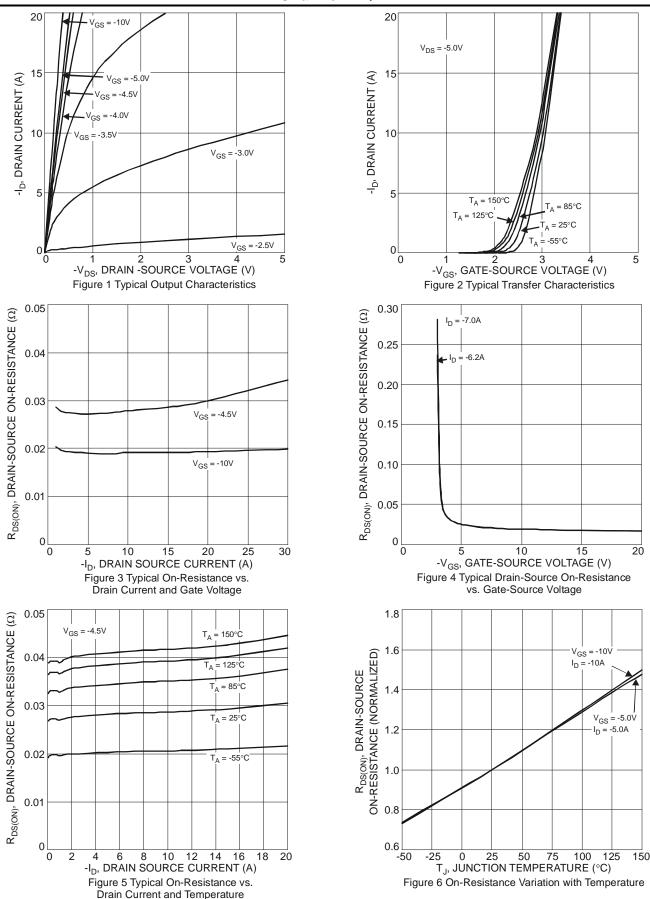
Figure 11 Gate-Source Voltage vs. Total Gate Charge



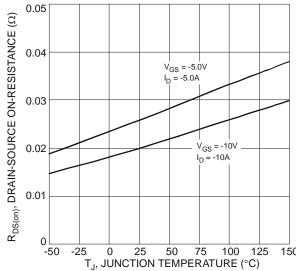


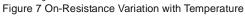


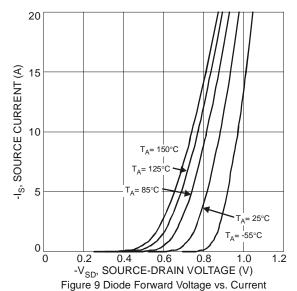
P-Channel - Q2











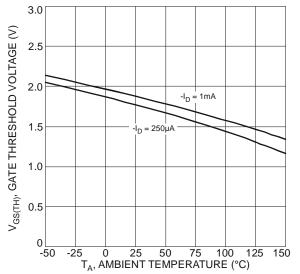
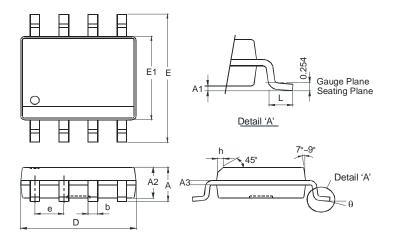


Figure 8 Gate Threshold Variation vs. Ambient Temperature



Package Outline Dimensions

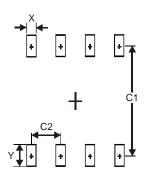
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| SO-8 | | | | | | |
|----------------------|----------|------|--|--|--|--|
| Dim | Min | Max | | | | |
| Α | - | 1.75 | | | | |
| A1 | 0.10 | 0.20 | | | | |
| A2 | 1.30 | 1.50 | | | | |
| А3 | 0.15 | 0.25 | | | | |
| b | 0.3 | 0.5 | | | | |
| D | 4.85 | 4.95 | | | | |
| Е | 5.90 | 6.10 | | | | |
| E1 | 3.85 | 3.95 | | | | |
| е | 1.27 Typ | | | | | |
| h | - | 0.35 | | | | |
| L | 0.62 | 0.82 | | | | |
| Θ | 0° 8° | | | | | |
| All Dimensions in mm | | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) | | | |
|------------|---------------|--|--|--|
| Х | 0.60 | | | |
| Y | 1.55 | | | |
| C1 | 5.4 | | | |
| C2 | 1.27 | | | |



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2013, Diodes Incorporated

www.diodes.com

ПОСТАВКА ЭЛЕКТРОННЫХ КОМПОНЕНТОВ

многоканальный

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001 Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru_4 moschip.ru_9